

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	16	(die or IC or dice or chip) near8 active near8 (test adj pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 14:51
L2	3	1 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:41
L3	31869	Micron.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 14:54
L5	2	((test or dummy) near pad) with (conductive near path) with (die dice chip element IC (integrated adj circuit)) with (wafer substrate) same (active adj portion)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 14:58
L6	53	((test or dummy) near pad) with (conductive near path)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 14:59
L7	10	3 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:02
L8	258	(bond adj pad) with (test adj pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:03
L9	3	8 with (top adj view)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:04

## EAST Search History

L10	6	bond\$6 with ((test or dummy) near pad) with active with (conductive interconnect or interconnecting interconnected) with (wafer substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:30
L11	235	bond\$6 with ((test or dummy) near pad) with (conductive interconnect or interconnecting interconnected)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:31
L12	380	Lunde.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:31
L13	13	3 and 12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:31
L14	4	13 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:37
L15	0	((test or tested or testing) near pad) with (active near surface) with path	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:36
L16	5	((test or tested or testing) near4 pad) with (active near surface) with path	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:36
L17	5	16 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:37

## EAST Search History

L18	4385	((257/620) or (257/786) or (257/690)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/10 15:39
L19	510	((test or testing or tested) near (pad or bond)) with (connect\$4) with (wafer substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:52
L20	363	19 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:52
L21	23	18 and 19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 15:52
L22	19	21 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 16:14
L23	2	("20010052786"   "5554940").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/10 16:02
L24	2	("20010052786"   "5554940").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/10 16:08
L25	5	("6534853").URPN.	USPAT	OR	ON	2006/04/10 16:08
L26	21	("5923047").URPN.	USPAT	OR	ON	2006/04/10 16:11
L27	4	("5003374"   "5047711"   "5285082"   "5684304").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/10 16:13
L28	2092	(438/14).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/10 16:13

## EAST Search History

L29	4758	((438/14) or (438/612)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/10 16:13
L30	24	19 and 29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 16:14
L31	14	30 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 16:14